GERRATING	APPLICA	BLE STAN	DARD								
RATING					°C (1)	TEMPERATURE			-10 °C TO 60) °C (2)	
CURRENT 0.0 A A (SIGNAL CONTACT) RANGE RELATIVE HUMINITY 85% mm (NOT DEWED)	RATING	VOLTAGE		100 V AC			RANGE		40 % TO 70		2)
SPECIFICATIONS TEST METHOD		CURRENT		0.5 A (SIGNAL CONTACT) (3)					RELATIVE HUMIDIT	y 85%	max
TIEM TEST METHOD REQUIREMENTS QT / CONSTRUCTION SERVERAL EXAMINATION VISUALLY AND BY MEASURING INSTRUMENT. ACCORDING TO DRAWING. X LECTRIC CHARACTERISTICS SONTACT RESISTANCE 100 m/40C OR 1000H2) SIGNAL CONTACT : 90 m/20MAX. X ELECTRIC CHARACTERISTICS SONTACT RESISTANCE 250 V DC. 1000 M/20C OR 1000H2) SIGNAL CONTACT : 90 m/20MAX. X MF CONTACT : 90 m/20MAX. X		CONTRICT	3 A (MF CONTACT)				(NOT E				
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SECONTACT RESISTANCE						NT.	ACCOR	DING TO DR	AWING.	<u> </u>	<u> </u>
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NSULATION RESISTANCE 250 V DC						T _c	CIONIAI	CONTACT	. 00 OMAY	Τ.,	Τ.
WECHANICAL CHARACTERISTICS	CONTACT RESISTANCE		100 mA(DC OR 1000Hz)							*	-
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#ECHANICAL DPERATION \$00 TIMES INSERTIONS AND EXTRACTIONS. (1) CONTACT RESISTANCE: SIGNAL CONTACT: 100 m \(2) MAX. MF CONTACT: 100 m \(2) MAX. MF CONTACT: 40 m \(2) MAX. MF CONTA	INSERTION AND WITHDRAWAL FORCES		MEASURED BY APPLICABLE CONNECTOR.								-
MF CONTACT : 40 m Q MAX. (2) NO DAMAGE, CRACK AND LOOSENESS OF PARTS. AUBRATION FREQUENCY 10 TO 55 TO 10Hz. APPROX 5min SINGLE AMPLITUDE: 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS. SHOCK 490 m/s², DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS. SHOCK 490 m/s², DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS. SINVIRONMENTAL CHARACTERISTICS DAMP HEAT EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h. STEADY STATE) REPID CHANGE OF TEMPERATURE -55 → +85 °C MINE CONTACT : 100 m Q MAX. REMPERATURE 100 m Q max. MF CONTACT : 40 m Q MAX. MF CONTACT : 100 m Q MAX. MF CONTACT : 40 m Q MAX. MF	MECHANICAL		500 TIMES INSERTIONS AND EXTRACTIONS.								+-
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